ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES ®	© Co	terial Compo pyright 2005. IPC, Bannoc atternational and Pan-Ameri	kburn, Illinois	. All rights reser	ition with lower	level p	arts, the	declaratio	n enco	mpasses all	l lower leve	el materials f	or which	the item is an assembly the manufacturer has is declaration.
IPC-1752-1 v1.02 IPC Web Site for Information on IPC http://www.ipc.org/IPC-175x			C-1752 Standard			n Type * ribute		Declaration Class * Class 4 - RoHS Yes/No, JIG Format Substances, Mfg Info						
Supplier Information														
Company Name * Anaren Microwave, Inc.		Company Unique ID		Unique ID A	uthority	Response Date * 2007-08-21		Response Document ID						
Contact Name * Michael Lugert		Title - Contact  Product Line Manager				Email - Contact * mlugert@anaren.com			Duplicate Contact -> Authorized Representative					
Authorized Representative * Michael Lugert		Title - Representative Phone - Representative * Product Line Manager (315) 432-8909 x1480		Email - Representative * mlugert@anaren.com			Supplier Comments or URL for Additional Information							
Requester Item Number		Mfr Item Number		Mfr Item Name		Effectiv	/e Date	Version	Manufa	acturing Site	Weig	ght	JOM	Unit Type
		XC0900L-03S		3dB Xinger	II Coupler, 0.8-1.0				East S	Syracuse	0.94	1 g	l	Each
Alternate Recommendation		XC0900L-03P		3dB Xinger	II Coupler, 0.8-1.0			Alternate Item Co		omments		•		
Manufacturing Proces	ss In	formation												
			Terminal B	,	J-STD-020 MSL Ra	iting	Peak Prod	•	Tempe <b>260</b> C			k Temperatur 30 seconds		er of Reflow Cycles
Comments					•					,			•	

Save the fields in this form to a file    Export Data    Import fields from a file into this form    Import Data	Clear all of the fields on this form Reset Form	Lock the fields on this form to prevent changes	Lock Supplier Fields						
RoHS Material Composition Declaration		Declaration Type *	Simplified						
RoHS Directive 2002/95/EC RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium									
Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.									
RoHS Declaration * 1 - Item(s) does not contain RoHS restricted substances per the definition above		Supplier Acceptance Accept	ed						
<b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition at above and checkboxes will appear below. Check all applicable exemptions.	pove except for defined RoHS exemptions, then s	elect the corresponding respon	se in the RoHS Declaration						
Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.	7c. Lead in electronic ceramic parts (e.g. piezoe	lectronic devices).							
2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg. in halophosphate lamps	8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations piezoelectronic devices).								
2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg. in triphosphate lamps with a normal lifetime	<ol><li>Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators</li></ol>								
2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg. in triphosphate lamps with long lifetime									
3. Mercury in straight fluorescent lamps for special purposes.	10b. Lead in lead/bronze bearing shells and bus	shes							
4. Mercury in other lamps not specifically mentioned in this list.	11. Lead used in compliant pin connector system	ms.							
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.	12. Lead as a coating material for a thermal conduction module c-ring.								
6a. Lead as an alloying element in steel containing up to 0.35% lead by weight.	13a. Lead in optical and filter glass.								
6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight.	13b. Cadmium in optical and filter glass.								
6c. Lead as an alloying element in copper containing up to 4% lead by weight.		. Lead in solders consisting of more than two elements for the connection between the pins and the ckage of microprocessors with a lead content of more than 80% and less than 85% by weight .							
7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).	15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.								
7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications.									
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Ac	cepted" on the Supplier Acceptance drop-do	wn. This will display the sig	nature area. Digitally sign						

the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Joint Industry Guide (JIG) Material Composition Declaration for Electronic Products

Instructions: Declare whether the item substances exceed the threshold levels shown in the table and report accordingly. Where threshold levels include the words "intentionally added", substances must be declared if they are added intentionally, regardless of threshold level. For each RoHS substance, identified with dual asterisks (\*\*), report the worst case PPM at the homogeneous material level and optionally the total weight of the substance in the item. For all remaining (non-RoHS) JIG A & B substances, and any additional substances, report the total weight and optionally the PPM at the part level for each item.

				JIG A auto	ofill - No		JIG B	autofill - No	0	All autofill - No
JIG	Category Name	Threshold Level	Above Threshold Level?	nold If yes, enter total we					iption of Use	
Level	As defined in the Joint Industry Guide	Intentionally added or PPM	Yes/No	Weight	UoM		PPM			
Α	Asbestos	Intentionally Added	No		mg					
Α	Certain Azo colorants	Intentionally Added	No		mg					
Α	Cadmium/Cadmium Compounds **	75 PPM or Intentionally Added	No		mg					
Α	Hexavalent Chromium/Hexavalent Chromium Compounds **	1000 PPM or Intentionally Added	No		mg					
Α	Lead/Lead Compounds **	1000 PPM or Intentionally Added	No		mg					
Α	Lead/Lead Compounds - PVC Cables and Wires Only **	300 PPM	No		mg					
Α	Mercury/Mercury Compounds **	1000 PPM or Intentionally Added	No		mg					
Α	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)	Intentionally Added	No		mg					
Α	Ozone Depleting Substances - Class II (HCFCs)	1000 PPM	No		mg					
Α	Polybrominated Biphenyls (PBBs) **	1000 PPM or Intentionally Added	No		mg					
Α	Polybrominated Diphenylethers (PBDEs) **	1000 PPM or Intentionally Added	No		mg					
Α	Polychlorinated Biphenyls (PCBs)	Intentionally Added	No		mg					
Α	Polychlorinated Naphthalenes ( > 3 chlorine atoms)	Intentionally Added	No		mg					
Α	Radioactive Substances	Intentionally Added	No		mg					
Α	Certain Shortchain Chlorinated Paraffins	Intentionally Added	No		mg					
Α	Tributyl Tin (TBT) and Triphenyl Tin (TPT)	Intentionally Added	No		mg					
Α	Tributyl Tin Oxide (TBTO)	Intentionally Added	No		mg					
В	Antimony/Antimony Compounds	1000 PPM	No		mg					
В	Arsenic/Arsenic Compounds	1000 PPM	No		mg					
В	Beryllium/Beryllium Compounds	1000 PPM	No		mg					
В	Bismuth/Bismuth Compounds	1000 PPM	No		mg					
В	Brominated Flame Retardants (other than PBBs or PBDEs)	1000 PPM	No		mg					
В	Nickel (external applications only)	1000 PPM	No		mg					
В	Certain Phthalates	1000 PPM	No		mg					
В	Selenium/Selenium Compounds	1000 PPM	No		mg					
В	Polyvinyl Chloride (PVC)	1000 PPM	No		mg					

## **OTHER Material Composition Declaration**

Requester Instructions: The requester can optionally include additional substances that must be declared for the item on this form. This is in addition to JIG Level A and JIG Level B substances. The requester should enter additional substances as well as the threshold levels that specify the substance at the item level.

Supplier Instructions: Explicitly declare whether the item exceed the threshold level by selecting Yes or No. If the maximum concentration of any substance exceeds the threshold levels defined by the requester, then the substance content must be reported in total weight and/or worst case PPM, along with a description of material use.

JIG	Category Name	Threshold Level
Other	As defined by the Requester	Defined by the Requester
+ -		

Add Other Material Composition to JIG Tab